

# <u>MMST3904</u>

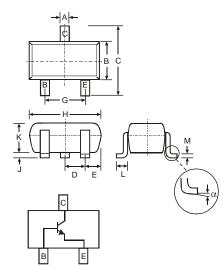
### NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

### Features

- Epitaxial Planar Die Construction
- Complementary PNP Type Available (MMST3906)
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability
- "Green" Device (Notes 3 and 4)

# **Mechanical Data**

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: See Diagram
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Marking Information: K2N See Page 4
- Ordering & Date Code Information: See Page 4
- Weight: 0.006 grams (approximate)



SOT-323				
Dim	Min Max			
Α	0.25	0.40		
В	1.15	1.35		
С	2.00 2.20			
D	0.65 Nominal			
Е	0.30	0.40		
G	1.20	1.40		
Н	1.80	2.20		
J	0.0	0.10		
к	0.90	1.00		
L	0.25	0.40		
м	0.10	0.18		
α	0°	8°		
All Dimensions in mm				

# Maximum Ratings @T<sub>A</sub> = 25<sup>°</sup>C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Collector-Base Voltage	V <sub>CBO</sub>	60	V	
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V	
Emitter-Base Voltage	V <sub>EBO</sub>	6.0	V	
Collector Current – Continuous (Note 1)	Ι <sub>C</sub>	200	mA	
Power Dissipation (Note 1)	Pd	200	mW	
Thermal Resistance, Junction to Ambient (Note 1)	R <sub>0JA</sub>	625	°C/W	
Operating and Storage Temperature Range	T <sub>j</sub> , T <sub>STG</sub>	-55 to +150	°C	

Notes: 1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout

document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com./products/lead\_free/index.php.

4. Product manufactured with Date Code 0627 (week 27, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0627 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

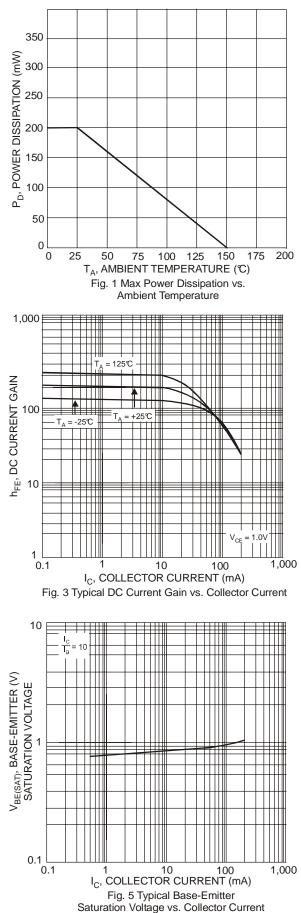


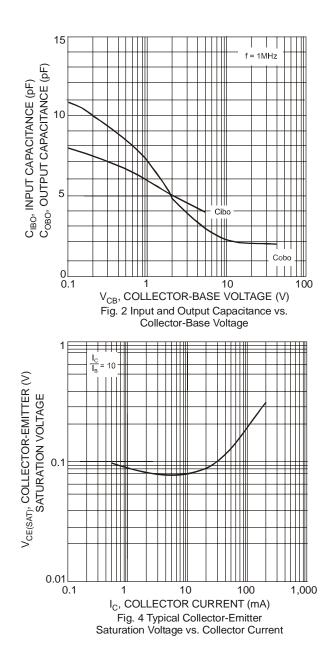
# Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 5)	· ·				•	
Collector-Base Breakdown Voltage	V <sub>(BR)CBO</sub>	60		V	$I_{C} = 10 \mu A, I_{E} = 0$	
Collector-Emitter Breakdown Voltage	V <sub>(BR)CEO</sub>	40		V	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0	
Emitter-Base Breakdown Voltage	V <sub>(BR)EBO</sub>	5.0		V	$I_{E} = 10 \mu A, I_{C} = 0$	
Collector Cutoff Current	I <sub>CEX</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
Base Cutoff Current	I <sub>BL</sub>	_	50	nA	$V_{CE} = 30V, V_{EB(OFF)} = 3.0V$	
ON CHARACTERISTICS (Note 5)						
DC Current Gain	h <sub>FE</sub>	40 70 100 60 30	 300 	_	$\begin{split} I_{C} &= 100 \mu A, V_{CE} = 1.0V \\ I_{C} &= 1.0 mA, V_{CE} = 1.0V \\ I_{C} &= 10 mA, V_{CE} = 1.0V \\ I_{C} &= 50 mA, V_{CE} = 1.0V \\ I_{C} &= 100 mA, V_{CE} = 1.0V \end{split}$	
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>		0.25 0.30	V	$I_{C} = 10mA, I_{B} = 1.0mA$ $I_{C} = 50mA, I_{B} = 5.0mA$	
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.65	0.85 0.95	V	$\begin{array}{ll} I_C = & 10mA, \ I_B = 1.0mA \\ I_C = & 50mA, \ I_B = 5.0mA \end{array}$	
SMALL SIGNAL CHARACTERISTICS			-			
Output Capacitance	C <sub>obo</sub>	_	4.0	pF	$V_{CB} = 5.0V$ , f = 1.0MHz, I <sub>E</sub> = 0	
Input Capacitance	Cibo	_	8.0	pF	$V_{EB} = 0.5V$ , f = 1.0MHz, I <sub>C</sub> = 0	
Input Impedance	h <sub>ie</sub>	1.0	10	kΩ		
Voltage Feedback Ratio	h <sub>re</sub>	0.5	8.0	x 10 <sup>-4</sup>	V <sub>CE</sub> = 10V, I <sub>C</sub> = 1.0mA,	
Small Signal Current Gain	h <sub>fe</sub>	100	400	_	f = 1.0MHz	
Output Admittance	h <sub>oe</sub>	1.0	40	μS		
Current Gain-Bandwith Product	f <sub>T</sub>	300		MHz	$V_{CE} = 20V, I_C = 10mA,$ f = 100MHz	
Noise Figure	NF		5.0	dB	$V_{CC} = 5.0V, I_C = 100\mu A,$ $R_S = 1.0k\Omega, f = 1.0MHz$	
SWITCHING CHARACTERISTICS			•	•		
Delay Time	t <sub>d</sub>	_	35	ns	V <sub>CC</sub> = 3.0V, I <sub>C</sub> = 10mA, V <sub>BE(OFF)</sub> = -0.5V, I <sub>B1</sub> = 1.0mA	
Rise Time	tr		35	ns		

Notes: 5. Short duration pulse test used to minimize self-heating effect.







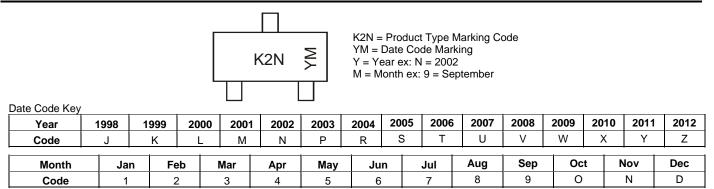


### Ordering Information (Notes 4 and 6)

Device	Packaging	Shipping
MMST3904-7-F	SOT-323	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

# **Marking Information**



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